Caution · Notice

Caution (Storage and Operating Conditions)
This product is designed for application in an ordinary environment (normal room temperature, humidity and atmospheric pressure). Do not use under the following conditions because all of these factors can deteriorate the characteristics or cause product failure and burn-out.
1. Corrosive gas or deoxidizing gas (Chlorine gas, Hydrogen sulfide gas, Ammonia gas, Sulfuric acid gas, Nitric oxide gas, etc.)
2. Volatile or flammable gas
3. Dusty conditions
4. Under vacuum, or under high or low pressure
5. Wet or humid conditions
6. Places with salt water, oils, chemical liquids or organic solvents
7. Strong vibrations
8. Other places where similar hazardous conditions exist

Caution (Others)
Be sure to provide an appropriate fail-safe function on your product to prevent secondary damage that may be caused by the abnormal function or the failure of our product.

Notice (Storage and Operating Conditions)
To keep solderability of product from declining, the following storage conditions are recommended.
1. Storage Condition:
   Temperature -10 to +40°C
   Humidity less than 75%RH (not dewing condition)
2. Storage Term:
   Use this product within 6 months after delivery by first-in and first-out stocking system.
3. Handling after Unpacking:
   After unpacking, promptly reseal this product or store it in a sealed container with a drying agent.

4. Storage Place:
   Do not store this product in corrosive gas (Sulfuric acid, Chlorine, etc.) or in direct sunlight.

Notice (Handling)
1. Do not give this product a strong press-force or a mechanical shock, because such mechanical forces may cause cracking or chipping of this ceramic product.
2. Rapid cooling or heating during soldering is not recommended such treatment may destroy the element.
3. Resin Coating
   Please select a resin material with minimum hardness. The shrinkage of the resin at heat treatment should be much less in order not to apply much stress to the product.
4. Location on Printed Circuit Board (PC Board)
   Choose a mounting position that minimizes the stress imposed on the chip during flexing or bending of the board.

Component Direction
(Worse) \[\rightarrow\] (Better)

Locate chip horizontal to the direction in which stress acts

Chip Mounting Close to Board Separation Point
Perforation Holes

Put this product on the PC Board near the Slit, not near the Perforation Holes. Keep this product on the PC Board away from the Separation Line.

Worst A-C-B-D Better